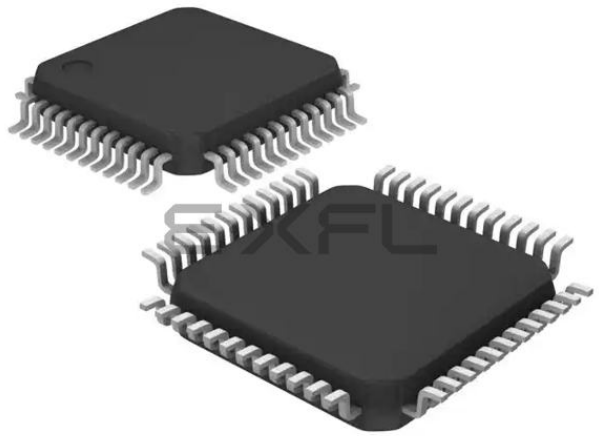

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	H8/300H
Core Size	16-Bit
Speed	20MHz
Connectivity	SCI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	30
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LFQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/df36014gfyv

Preface

The H8/36024 Group and H8/36014 Group are single-chip microcomputers made up of the high-speed H8/300H CPU employing Renesas Technology original architecture as their cores, and the peripheral functions required to configure a system. The H8/300H CPU has an instruction set that is compatible with the H8/300 CPU.

Target Users: This manual was written for users who will be using the H8/36024 Group and H8/36014 Group in the design of application systems. Target users are expected to understand the fundamentals of electrical circuits, logical circuits, and microcomputers.

Objective: This manual was written to explain the hardware functions and electrical characteristics of the H8/36024 Group and H8/36014 Group to the target users. Refer to the H8/300H Series Software Manual for a detailed description of the instruction set.

Notes on reading this manual:

- In order to understand the overall functions of the chip
  Read the manual according to the contents. This manual can be roughly categorized into parts on the CPU, system control functions, peripheral functions and electrical characteristics.
- In order to understand the details of the CPU's functions
  Read the H8/300H Series Software Manual.
- In order to understand the details of a register when its name is known
  Read the index that is the final part of the manual to find the page number of the entry on the register. The addresses, bits, and initial values of the registers are summarized in section 17, List of Registers.
  Example: Bit order: The MSB is on the left and the LSB is on the right.

Notes:

When using the on-chip emulator (E7, E8) for H8/36014 program development and debugging, the following restrictions must be noted.

1. The $\overline{\text{NMI}}$ pin is reserved for the E7 or E8, and cannot be used.
2. Area H’7000 to H’7FFF is used by the E7 or E8, and is not available to the user.
3. Area H’F780 to H’FB7F must on no account be accessed.

Table 2.3 Arithmetic Operations Instructions (2)

Instruction	Size*	Function
DIVXS	B/W	Rd ÷ Rs → Rd Performs signed division on data in two general registers: either 16 bits ÷ 8 bits → 8-bit quotient and 8-bit remainder or 32 bits ÷ 16 bits → 16-bit quotient and 16-bit remainder.
CMP	B/W/L	Rd – Rs, Rd – #IMM Compares data in a general register with data in another general register or with immediate data, and sets CCR bits according to the result.
NEG	B/W/L	0 – Rd → Rd Takes the two's complement (arithmetic complement) of data in a general register.
EXTU	W/L	Rd (zero extension) → Rd Extends the lower 8 bits of a 16-bit register to word size, or the lower 16 bits of a 32-bit register to longword size, by padding with zeros on the left.
EXTS	W/L	Rd (sign extension) → Rd Extends the lower 8 bits of a 16-bit register to word size, or the lower 16 bits of a 32-bit register to longword size, by extending the sign bit.

Note: * Refers to the operand size.
B: Byte
W: Word
L: Longword

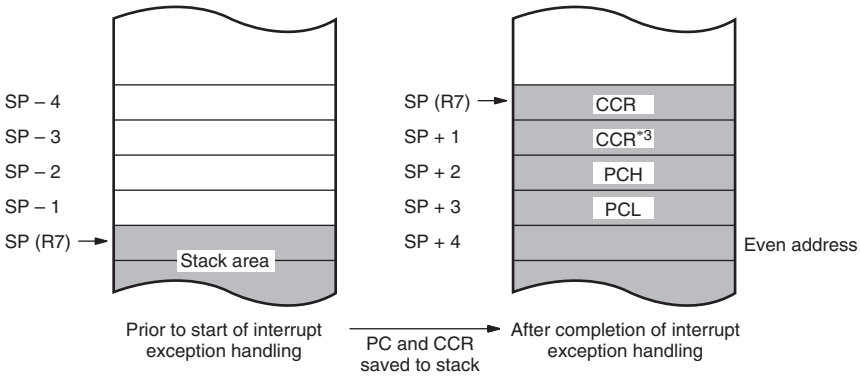
Table 2.4 Logic Operations Instructions

Instruction	Size*	Function
AND	B/W/L	Rd ∧ Rs → Rd, Rd ∧ #IMM → Rd Performs a logical AND operation on a general register and another general register or immediate data.
OR	B/W/L	Rd ∨ Rs → Rd, Rd ∨ #IMM → Rd Performs a logical OR operation on a general register and another general register or immediate data.
XOR	B/W/L	Rd ⊕ Rs → Rd, Rd ⊕ #IMM → Rd Performs a logical exclusive OR operation on a general register and another general register or immediate data.
NOT	B/W/L	¬ (Rd) → (Rd) Takes the one's complement of general register contents.

Table 2.8 System Control Instructions

Instruction	Size*	Function
TRAPA	—	Starts trap-instruction exception handling.
RTE	—	Returns from an exception-handling routine.
SLEEP	—	Causes a transition to a power-down state.
LDC	B/W	(EAs) → CCR Moves the source operand contents to the CCR. The CCR size is one byte, but in transfer from memory, data is read by word access.
STC	B/W	CCR → (EAd), EXR → (EAd) Transfers the CCR contents to a destination location. The condition code register size is one byte, but in transfer to memory, data is written by word access.
ANDC	B	CCR ∧ #IMM → CCR, EXR ∧ #IMM → EXR Logically ANDs the CCR with immediate data.
ORC	B	CCR ∨ #IMM → CCR, EXR ∨ #IMM → EXR Logically ORs the CCR with immediate data.
XORC	B	CCR ⊕ #IMM → CCR, EXR ⊕ #IMM → EXR Logically XORs the CCR with immediate data.
NOP	—	PC + 2 → PC Only increments the program counter.

Note: * Refers to the operand size.
B: Byte
W: Word



Legend:
PCH: Upper 8 bits of program counter (PC)
PCL: Lower 8 bits of program counter (PC)
CCR: Condition code register
SP: Stack pointer

Notes: 1. PC shows the address of the first instruction to be executed upon return from the interrupt handling routine.
2. Register contents must always be saved and restored by word length, starting from an even-numbered address.
3. Ignored when returning from the interrupt handling routine.

Figure 3.2 Stack Status after Exception Handling

3.4.4 Interrupt Response Time

Table 3.2 shows the number of wait states after an interrupt request flag is set until the first instruction of the interrupt handling-routine is executed.

Table 3.2 Interrupt Wait States

Item	States	Total
Waiting time for completion of executing instruction*	1 to 23	15 to 37
Saving of PC and CCR to stack	4	
Vector fetch	2	
Instruction fetch	4	
Internal processing	4	

Note: * Not including EEPMOV instruction.

6.1.2 System Control Register 2 (SYSCR2)

SYSCR2 controls the power-down modes, as well as SYSCR1.

Bit	Bit Name	Initial Value	R/W	Description
7	SMSEL	0	R/W	Sleep Mode Selection This bit selects the mode to transit after the execution of a SLEEP instruction, as well as bit SSBY of SYSCR1. For details, see table 6.2.
6	—	0	—	Reserved This bit is always read as 0.
5	DTON	0	R/W	Direct Transfer on Flag This bit selects the mode to transit after the execution of a SLEEP instruction, as well as bit SSBY of SYSCR1. For details, see table 6.2.
4	MA2	0	R/W	Active Mode Clock Select 2 to 0
3	MA1	0	R/W	These bits select the operating clock frequency in active and sleep modes. The operating clock frequency changes to the set frequency after the SLEEP instruction is executed.
2	MA0	0	R/W	0XX: ϕ_{osc} 100: ϕ_{osc}/8 101: ϕ_{osc}/16 110: ϕ_{osc}/32 111: ϕ_{osc}/64
1, 0	—	All 0	—	Reserved These bits are always read as 0.

Legend: X : Don't care.

Table 7.4 Reprogram Data Computation Table

Program Data	Verify Data	Reprogram Data	Comments
0	0	1	Programming completed
0	1	0	Reprogram bit
1	0	1	—
1	1	1	Remains in erased state

Table 7.5 Additional-Program Data Computation Table

Reprogram Data	Verify Data	Additional-Program Data	Comments
0	0	0	Additional-program bit
0	1	1	No additional programming
1	0	1	No additional programming
1	1	1	No additional programming

Table 7.6 Programming Time

n (Number of Writes)	Programming Time	In Additional Programming	Comments
1 to 6	30	10	
7 to 1,000	200	—	

Note: Time shown in µs.

7.4.2 Erase/Erase-Verify

When erasing flash memory, the erase/erase-verify flowchart shown in figure 7.4 should be followed.

1. Prewriting (setting erase block data to all 0s) is not necessary.
2. Erasing is performed in block units. Make only a single-bit specification in the erase block register (EBR1). To erase multiple blocks, each block must be erased in turn.
3. The time during which the E bit is set to 1 is the flash memory erase time.
4. The watchdog timer (WDT) is set to prevent overerasing due to program runaway, etc. An overflow cycle of approximately 19.8 ms is allowed.

5. For a dummy write to a verify address, write 1-byte data H'FF to an address whose lower two bits are B'00. Verify data can be read in longwords from the address to which a dummy write was performed.
6. If the read data is not erased successfully, set erase mode again, and repeat the erase/erase-verify sequence as before. The maximum number of repetitions of the erase/erase-verify sequence is 100.

7.4.3 Interrupt Handling when Programming/Erasing Flash Memory

All interrupts, including the $\overline{\text{NMI}}$ interrupt, are disabled while flash memory is being programmed or erased, or while the boot program is executing, for the following three reasons:

1. Interrupt during programming/erasing may cause a violation of the programming or erasing algorithm, with the result that normal operation cannot be assured.
2. If interrupt exception handling starts before the vector address is written or during programming/erasing, a correct vector cannot be fetched and the CPU malfunctions.
3. If an interrupt occurs during boot program execution, normal boot mode sequence cannot be carried out.

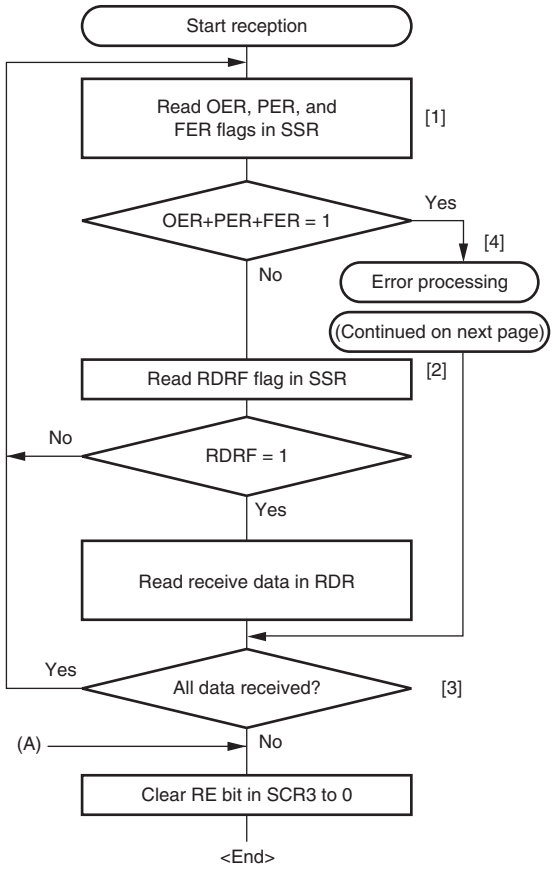
Bit	Bit Name	Initial Value	R/W	Description
1	IOA1	0	R/W	I/O Control A1 and A0
0	IOA0	0	R/W	When IOA2 = 0, 00: No output at compare match 01: 0 output to the FTIOA pin at GRA compare match 10: 1 output to the FTIOA pin at GRA compare match 11: Output toggles to the FTIOA pin at GRA compare match When IOA2 = 1, 00: Input capture at rising edge of the FTIOA pin 01: Input capture at falling edge of the FTIOA pin 1X: Input capture at rising and falling edges of the FTIOA pin

Legend X: Don't care.

11.3.6 Timer I/O Control Register 1 (TIOR1)

TIOR1 selects the functions of GRC and GRD, and specifies the functions of the FTIOC and FTIOD pins.

Bit	Bit Name	Initial Value	R/W	Description
7	—	1	—	Reserved This bit is always read as 1.
6	IOD2	0	R/W	I/O Control D2 Selects the GRD function. 0: GRD functions as an output compare register 1: GRD functions as an input capture register



[1] Read the OER, PER, and FER flags in SSR to identify the error. If a receive error occurs, performs the appropriate error processing.

[2] Read SSR and check that RDRF = 1, then read the receive data in RDR. The RDRF flag is cleared automatically.

[3] To continue serial reception, before the stop bit for the current frame is received, read the RDRF flag and read RDR.
The RDRF flag is cleared automatically.

[4] If a receive error occurs, read the OER, PER, and FER flags in SSR to identify the error. After performing the appropriate error processing, ensure that the OER, PER, and FER flags are all cleared to 0. Reception cannot be resumed if any of these flags are set to 1. In the case of a framing error, a break can be detected by reading the value of the input port corresponding to the RxD pin.

Figure 13.8 Sample Serial Reception Data Flowchart (Asynchronous Mode)(1)

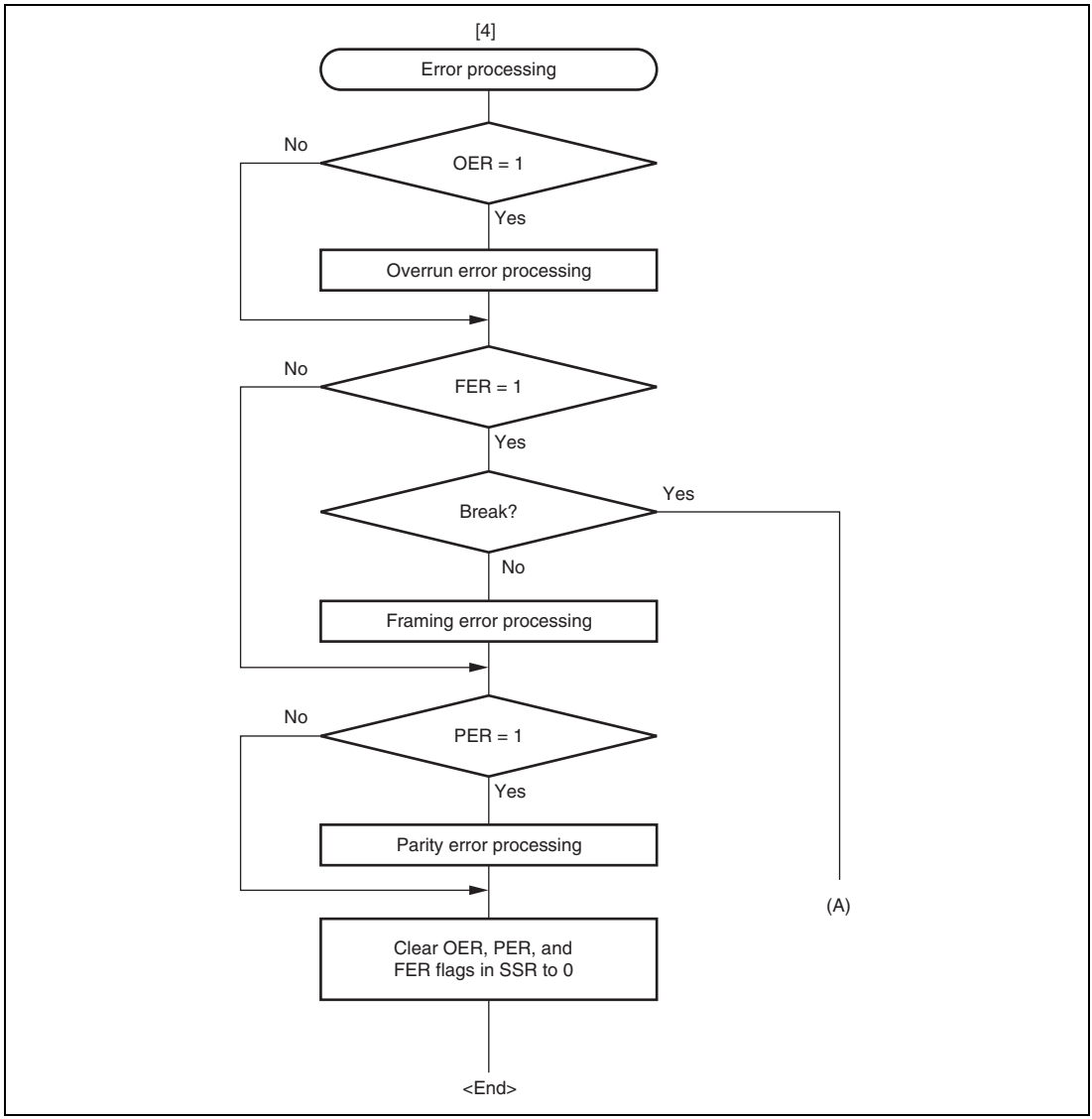


Figure 13.8 Sample Serial Reception Data Flowchart (Asynchronous Mode)(2)

Bit	Bit Name	Initial Value	R/W	Description	
2	CH2	0	R/W	Channel Select 0 to 2	
1	CH1	0	R/W	Select analog input channels.	
0	CH0	0	R/W	When SCAN = 0	When SCAN = 1
				X00: AN0	X00: AN0
				X01: AN1	X01: AN0 to AN1
				X10: AN2	X10: AN0 to AN2
				X11: AN3	X11: AN0 to AN3

Legend X: Don't care.

14.3.3 A/D Control Register (ADCR)

ADCR enables A/D conversion started by an external trigger signal.

Bit	Bit Name	Initial Value	R/W	Description
7	TRGE	0	R/W	Trigger Enable A/D conversion is started at the falling edge and the rising edge of the external trigger signal ($\overline{\text{ADTRG}}$) when this bit is set to 1. The selection between the falling edge and rising edge of the external trigger pin ($\overline{\text{ADTRG}}$) conforms to the WPEG5 bit in the interrupt edge select register 2 (IEGR2)
6 to 1	—	All 1	—	Reserved These bits are always read as 1.
0	—	0	R/W	Reserved Do not set this bit to 1, though the bit is readable/writable.

15.3 Operation

15.3.1 Power-On Reset Circuit

Figure 15.2 shows the timing of the operation of the power-on reset circuit. As the power-supply voltage rises, the capacitor which is externally connected to the $\overline{RES}$ pin is gradually charged via the on-chip pull-up resistor (typ. 150 kΩ). Since the state of the $\overline{RES}$ pin is transmitted within the chip, the prescaler S and the entire chip are in their reset states. When the level on the $\overline{RES}$ pin reaches the specified value, the prescaler S is released from its reset state and it starts counting. The OVF signal is generated to release the internal reset signal after the prescaler S has counted 131,072 clock (ϕ) cycles. The noise cancellation circuit of approximately 100 ns is incorporated to prevent the incorrect operation of the chip by noise on the $\overline{RES}$ pin.

To achieve stable operation of this LSI, the power supply needs to rise to its full level and settles within the specified time. The maximum time required for the power supply to rise and settle after power has been supplied (t_{PWON}) is determined by the oscillation frequency (f_{OSC}) and capacitance which is connected to $\overline{RES}$ pin ($C_{\overline{RES}}$). If t_{PWON} means the time required to reach 90 % of power supply voltage, the power supply circuit should be designed to satisfy the following formula.

$$t_{PWON}\ (\text{ms}) \leq 90 \times C_{\overline{RES}}\ (\mu\text{F}) + 162/f_{OSC}\ (\text{MHz})$$

($t_{PWON} \leq 3000$ ms, $C_{\overline{RES}} \geq 0.22$ µF, and $f_{OSC} = 10$ in 2-MHz to 10-MHz operation)

Note that the power supply voltage (Vcc) must fall below Vpor = 100 mV and rise after charge on the $\overline{RES}$ pin is removed. To remove charge on the $\overline{RES}$ pin, it is recommended that the diode should be placed near Vcc. If the power supply voltage (Vcc) rises from the point above Vpor, a power-on reset may not occur.

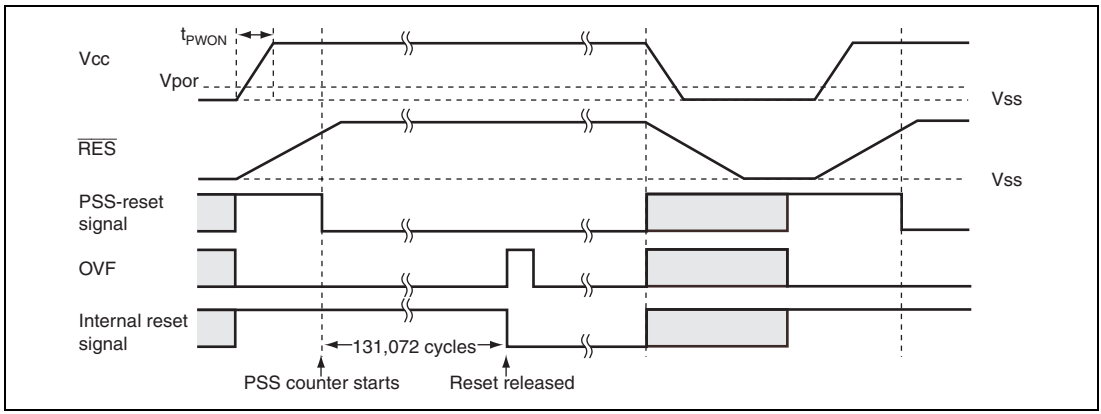


Figure 15.2 Operational Timing of Power-On Reset Circuit

Register Name	Abbre-viation	Bit No	Address	Module Name	Data Bus Width	Access State
Interrupt edge select register 2	IEGR2	8	H'FFF3	Interrupts	8	2
Interrupt enable register 1	IENR1	8	H'FFF4	Interrupts	8	2
Interrupt flag register 1	IRR1	8	H'FFF6	Interrupts	8	2
Wake-up interrupt flag register	IWPR	8	H'FFF8	Interrupts	8	2
Module standby control register 1	MSTCR1	8	H'FFF9	Power-down	8	2
Module standby control register 2	MSTCR2	8	H'FFFA	Power-down	8	2

Notes: 1. LVDC: Low-voltage detection circuits (optional)
2. Only word access can be used.
3. WDT: Watchdog timer

Register Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module Name
GRC	GRC15	GRC14	GRC13	GRC12	GRC11	GRC10	GRC9	GRC8	Timer W
	GRC7	GRC6	GRC5	GRC4	GRC3	GRC2	GRC1	GRC0	
GRD	GRD15	GRD14	GRD13	GRD12	GRD11	GRD10	GRD9	GRD8	
	GRD7	GRD6	GRD5	GRD4	GRD3	GRD2	GRD1	GRD0	
FLMCR1	—	SWE	ESU	PSU	EV	PV	E	P	ROM
FLMCR2	FLER	—	—	—	—	—	—	—	
EBR1	—	—	—	EB4	EB3	EB2	EB1	EB0	
FENR	FLSHE	—	—	—	—	—	—	—	
TCRV0	CMIEB	CMIEA	OVIE	CCLR1	CCLR0	CKS2	CKS1	CKS0	Timer V
TCSRV	CMFB	CMFA	OVF	—	OS3	OS2	OS1	OS0	
TCORA	TCORA7	TCORA6	TCORA5	TCORA4	TCORA3	TCORA2	TCORA1	TCORA0	
TCORB	TCORB7	TCORB6	TCORB5	TCORB4	TCORB3	TCORB2	TCORB1	TCORB0	
TCNTV	TCNTV7	TCNTV6	TCNTV5	TCNTV4	TCNTV3	TCNTV2	TCNTV1	TCNTV0	
TCRV1	—	—	—	TVEG1	TVEG0	TRGE	—	ICKS0	
SMR	COM	CHR	PE	PM	STOP	MP	CKS1	CKS0	SCI3
BRR	BRR7	BRR6	BRR5	BRR4	BRR3	BRR2	BRR1	BRR0	
SCR3	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0	
TDR	TDR7	TDR6	TDR5	TDR4	TDR3	TDR2	TDR1	TDR0	
SSR	TDRE	RDRF	OER	FER	PER	TEND	MPBR	MPBT	
RDR	RDR7	RDR6	RDR5	RDR4	RDR3	RDR2	RDR1	RDR0	
ADDRA	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	A/D converter
	AD1	AD0	—	—	—	—	—	—	
ADDRB	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	
	AD1	AD0	—	—	—	—	—	—	
ADDRC	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	
	AD1	AD0	—	—	—	—	—	—	
ADDRD	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	
	AD1	AD0	—	—	—	—	—	—	
ADCSR	ADF	ADIE	ADST	SCAN	CKS	CH2	CH1	CH0	
ADCR	TRGE	—	—	—	—	—	—	—	
TCSRWD	B6WI	TCWE	B4WI	TCSRWE	B2WI	WDON	B0WI	WRST	WDT*
TCWD	TCWD7	TCWD6	TCWD5	TCWD4	TCWD3	TCWD2	TCWD1	TCWD0	
TMWD	—	—	—	—	CKS3	CKS2	CKS1	CKS0	

17.3 Register States in Each Operating Mode

Register Name	Reset	Active	Sleep	Subsleep	Standby	Module
SMR_3	Initialized	—	—	Initialized	Initialized	SCI3_3
BRR_3	Initialized	—	—	Initialized	Initialized	
SCR3_3	Initialized	—	—	Initialized	Initialized	
TDR_3	Initialized	—	—	Initialized	Initialized	
SSR_3	Initialized	—	—	Initialized	Initialized	
RDR_3	Initialized	—	—	Initialized	Initialized	
SMCR	Initialized	—	—	Initialized	Initialized	
LVDCR	Initialized	—	—	—	—	LVDC (optional)
LVDSR	Initialized	—	—	—	—	
SMR_2	Initialized	—	—	Initialized	Initialized	SCI3_2
BRR_2	Initialized	—	—	Initialized	Initialized	
SCR3_2	Initialized	—	—	Initialized	Initialized	
TDR_2	Initialized	—	—	Initialized	Initialized	
SSR_2	Initialized	—	—	Initialized	Initialized	
RDR_2	Initialized	—	—	Initialized	Initialized	
TMRW	Initialized	—	—	—	—	Timer W
TCRW	Initialized	—	—	—	—	
TIERW	Initialized	—	—	—	—	
TSRW	Initialized	—	—	—	—	
TIOR0	Initialized	—	—	—	—	
TIOR1	Initialized	—	—	—	—	
TCNT	Initialized	—	—	—	—	
GRA	Initialized	—	—	—	—	
GRB	Initialized	—	—	—	—	
GRC	Initialized	—	—	—	—	
GRD	Initialized	—	—	—	—	
FLMCR1	Initialized	—	—	Initialized	Initialized	ROM
FLMCR2	Initialized	—	—	—	—	
EBR1	Initialized	—	—	Initialized	Initialized	
FENR	Initialized	—	—	—	—	

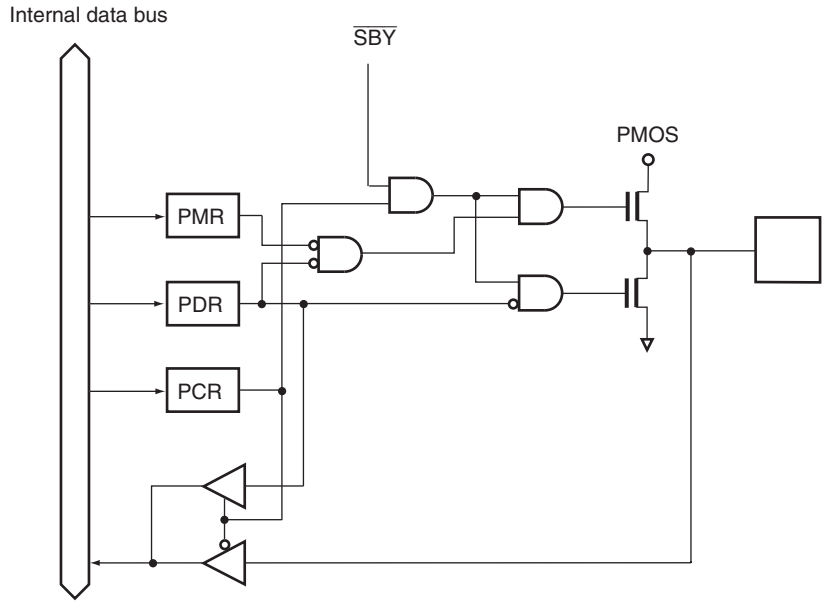
Item	Symbol	Applicable Pins	Test Condition	Values Min	Typ	Max	Unit	Notes
Pull-up MOS current	$-I_p$	P12 to P10, P17 to P14, P55 to P50	V_{CC} = 5.0 V, V_{IN} = 0.0 V	50.0	—	300.0	µA	
			V_{CC} = 3.0 V, V_{IN} = 0.0 V	—	60.0	—		Reference value
Input capacitance	C_{in}	All input pins except power supply pins	f = 1 MHz, V_{IN} = 0.0 V, T_a = 25°C	—	—	15.0	pF	
Active mode current consumption	I_{OPE1}	V_{CC}	Active mode 1 V_{CC} = 5.0 V, f_{OSC} = 20 MHz	—	15.0	30.0	mA	*2
			Active mode 1 V_{CC} = 3.0 V, f_{OSC} = 10 MHz	—	8.0	—		*2 Reference value
	I_{OPE2}	V_{CC}	Active mode 2 V_{CC} = 5.0 V, f_{OSC} = 20 MHz	—	1.8	3.0	mA	*2
			Active mode 2 V_{CC} = 3.0 V, f_{OSC} = 10 MHz	—	1.2	—		*2 Reference value
Sleep mode current consumption	I_{SLEEP1}	V_{CC}	Sleep mode 1 V_{CC} = 5.0 V, f_{OSC} = 20 MHz	—	11.5	22.5	mA	*2
			Sleep mode 1 V_{CC} = 3.0 V, f_{OSC} = 10 MHz	—	6.5	—		*2 Reference value
	I_{SLEEP2}	V_{CC}	Sleep mode 2 V_{CC} = 5.0 V, f_{OSC} = 20 MHz	—	1.7	2.7	mA	*2
			Sleep mode 2 V_{CC} = 3.0 V, f_{OSC} = 10 MHz	—	1.1	—		*2 Reference value
Standby mode current consumption	I_{STBY}	V_{CC}		—	—	5.0	µA	*2

Appendix A Instruction Set

A.1 Instruction List

Operand Notation

Symbol	Description
Rd	General (destination*) register
Rs	General (source*) register
Rn	General register*
ERd	General destination register (address register or 32-bit register)
ERs	General source register (address register or 32-bit register)
ERn	General register (32-bit register)
(EAd)	Destination operand
(EAs)	Source operand
PC	Program counter
SP	Stack pointer
CCR	Condition-code register
N	N (negative) flag in CCR
Z	Z (zero) flag in CCR
V	V (overflow) flag in CCR
C	C (carry) flag in CCR
disp	Displacement
→	Transfer from the operand on the left to the operand on the right, or transition from the state on the left to the state on the right
+	Addition of the operands on both sides
–	Subtraction of the operand on the right from the operand on the left
×	Multiplication of the operands on both sides
÷	Division of the operand on the left by the operand on the right
∧	Logical AND of the operands on both sides
∨	Logical OR of the operands on both sides
⊕	Logical exclusive OR of the operands on both sides
¬	NOT (logical complement)



Legend
PMR: Port mode register
PDR: Port data register
PCR: Port control register

Figure B.9 Port 5 Block Diagram (P57, P56) (H8/36014)

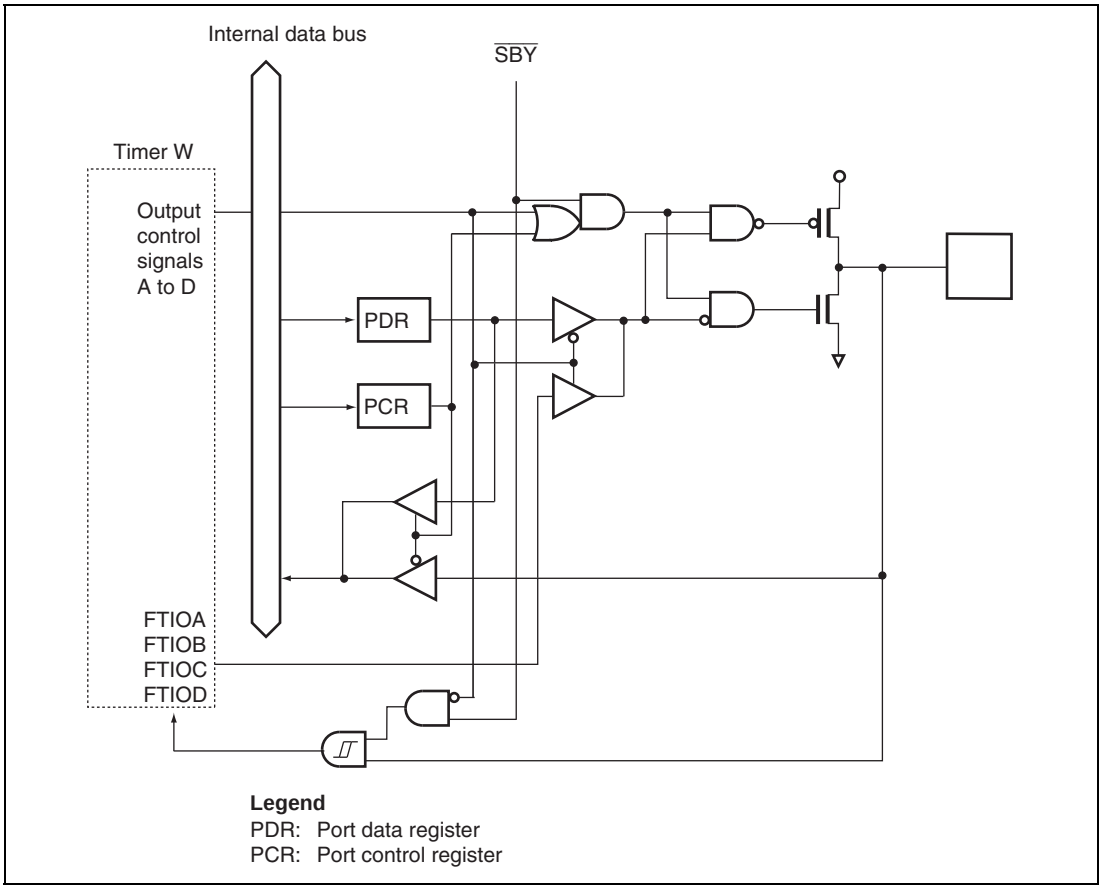


Figure B.21 Port 8 Block Diagram (P84 to P81)